

11/18/08



11-21-2008



Docket No.: 062807-0539

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To the Director of the U. S. Patent and Trademark Office

Documents or the new address(es) below.

1. Name of Conveying Party(ies)
 Hidetoshi MOROKUMA, Akiyuki SUGIYAMA, Ryoichi MATSUOKA, Takumichi SUTANI, Yasutaka TOYODA

Additional name(s) of conveying party(ies) attached? Yes No

2. Name and address of receiving party(ies)
 Name: HITACHI HIGH-TECHNOLOGIES CORPORATION
 Internal Address:
 Address: 24-14, Nishi-Shimbashi 1-chome, Minato-ku, Tokyo JAPAN

3. Nature of Conveyance/Execution Date(s)

Execution Date(s): August 6, 2008, July 29, 2008, July 29, 2008, July 30, 2008 and August 21, 2008 (respectively)

Assignment Merger
 Security Agreement Change of Name
 Joint Research Agreement
 Government Interest Assignment
 Executive Order 9424, Confirmatory License
 Other

Additional name(s) & address(es) attached? Yes No

4. Application or patent number(s):
 A. Patent Application No(s).
 12/279,564

Additional numbers attached? Yes No

This document is being filed together with a new application.
 B. Patent No(s).

5. Name and address to whom correspondence concerning document should be mailed:

Name: MCDERMOTT WILL & EMERY LLP
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6. Total number of applications and patents involved: 1

7. Total fee (37 CFR 1.21(h) & 3.41) \$40.00

Authorized to be charged by credit card
 Authorized to be charged to deposit account
 Enclosed
 None required (government interest not affecting title)

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9. Signature.
Keith E. George 34,111

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 01 EC:8021 40.00 DA
 Signature: *Keith E. George* Date: November 18, 2008

Name and Registration No. of Person Signing

Total number of pages including cover sheet, attachments and documents: 2

ASSIGNMENT (讓渡証)

As a below named inventor, I hereby declare that:

IN CONSIDERATION of the sum of One Dollar (\$1.00) or the equivalent thereof, and other good and valuable consideration paid to me citizen of Japan by HITACHI HIGH-TECHNOLOGIES CORPORATION, a corporation organized under the laws of Japan, located at 24-14, Nishi-Shimbashi 1-chome, Minato-ku, Tokyo, Japan, receipt of which is hereby acknowledged I do hereby sell and assign to said HITACHI HIGH-TECHNOLOGIES CORPORATION, its successors and assigns, all my right, title and interest, in and for the United States of America, in and to

SAMPLE DIMENSION INSPECTING/MEASURING METHOD AND SAMPLE DIMENSION INSPECTING/MEASURING APPARATUS

invented by me (if only one is named below) or us (if plural inventors are named below) and described in the application for United States Letters Patent therefor, executed on even date herewith, and all United States Letters Patent which may be granted therefor, and all divisions, continuations and extensions thereof, the said interest being the entire ownership of the said Letters Patent when granted, to be held and enjoyed by said HITACHI HIGH-TECHNOLOGIES CORPORATION, its successors, assigns or other legal representatives, to the full end of term for which said Letters Patent may be granted, as fully and entirely as the same would have been held and enjoyed by me or us if this assignment and sale had not been made;

And I hereby agree to sign and execute any further documents or instruments which may be necessary, lawful, and proper in the prosecution of the above-named application or in the preparation and prosecution of any continuing, continuation-in-part, substitute, divisional, renewal, reviewed or reissue applications or in any amendment, extension, or interference proceedings, or otherwise to secure the title thereto in said assignee;

And I do hereby authorize and request the Commissioner of Patents to issue said Letters Patent to said HITACHI HIGH-TECHNOLOGIES CORPORATION.

Signed on the date(s) indicated aside signatures:

	INVENTOR(S) (発明者フルネームサイン)	Date Signed (署名日)
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5)	<u>Yasutaka Toyoda</u> Yasutaka TOYODA	<u>8/21/2008</u>
6)	_____	_____
7)	_____	_____
8)	_____	_____
9)	_____	_____
10)	_____	_____